

Green Innovation Report

Juniper Networks, Inc. - 2024

ISIN: US48203R1041, **Ticker:** JNPR, **Country:** US, **Sector:** Communications Equipment

This report evaluates the green innovation activities of the company over the past decade, based on inventions published in green technology areas defined by the [IPC Green Inventory](#). This inventory, established by the World Intellectual Property Organization, identifies technologies aligned with the United Nations' definition of Environmentally Sound Technologies. These innovations contribute to mitigating humanity's impact on climate change in support of the Sustainable Development Goals.

Innovation Metrics

Invention Count (last 12 months)

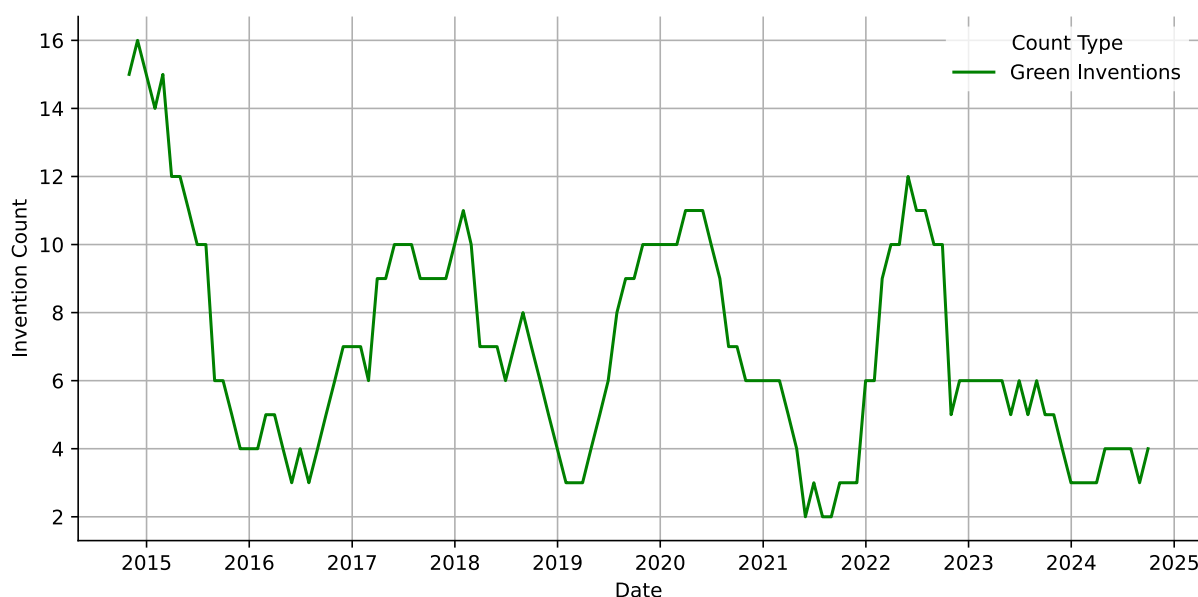
194 Inventions

Green Invention Count (last 12 months)

4 Green Inventions

Each invention reflects a substantial investment of R&D and legal resources. Consequently, green inventions provide a reliable and high-integrity metric for measuring a company's innovation efforts in green technologies and sustainability.

Rolling 1-Year Invention Count

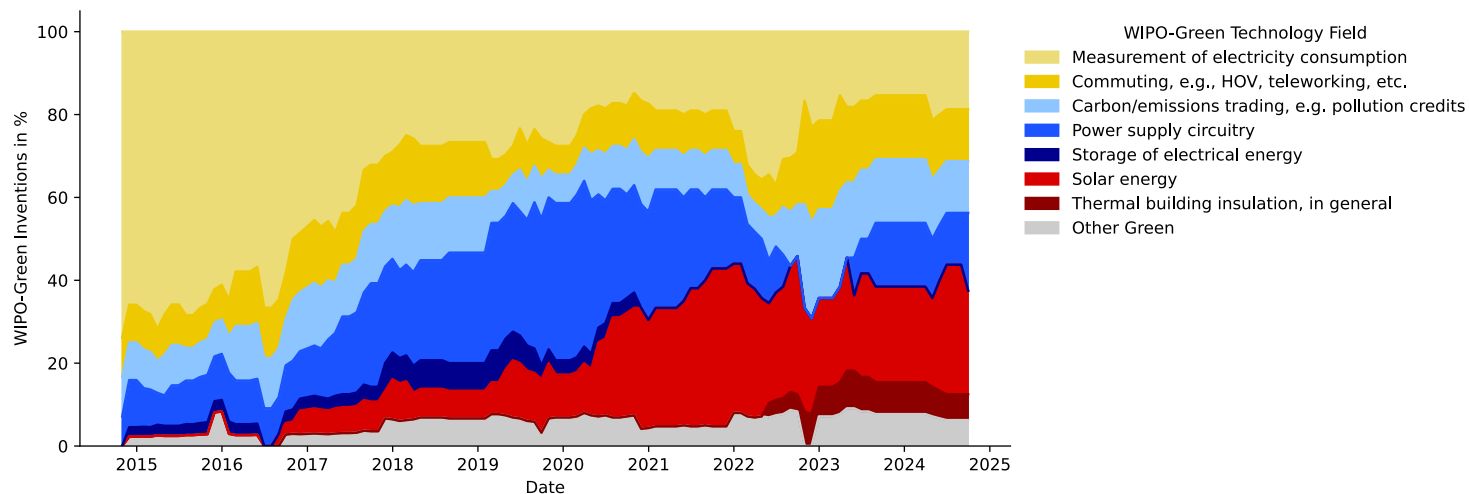


The graph above illustrates the number of green inventions published by the company over the past decade. Data is presented monthly, with each point representing the total green invention count for the preceding 12 months.

Green Technology Footprint

The graph below showcases the temporal distribution of the company's green innovation activity across technology fields listed in the IPC Green Inventory. This distribution highlights the green technology footprint and its evolution as part of the company's innovation strategy.

Rolling 3-Year WIPO-Green Footprint



The table below provides a quantitative analysis of the growth and significance of the company's key green technology fields. For each field, the most frequently appearing keywords in recent inventions offer valuable insights into the company's green innovation activities.

WIPO-Green Technology Field	Absolute Growth (3y)	Percentage of Green Inventions (3y)	Keywords (3y)
Solar energy	4	25.0%	semiconductor package, semiconductor package size, package size reduction, lidless semiconductor package, heterogeneous integration
Measurement of electricity consumption	3	18.8%	thermal test vehicle, removable module, hybrid circuit thermal, circuit thermal test, accurate insertion count
Power supply circuitry	3	18.8%	power supply unit, power supply, redundant power supply, redundant power architecture, power drawn
Commuting, e.g., HOV, teleworking, etc.	2	12.5%	network management, multiple customer facing, customer facing platform, conversation interface, contact level touchpoints
Thermal building insulation, in general	1	6.2%	toolless mounting

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